

~~Furthermore, because of the inherently strong covering power~~
of the molded plastic film, the connection between the
circuits on the surface and the back of the plastic film
cannot be readily formed, or the resonant circuit once
established cannot be easily destroyed, i.e., deactivation of
resonant frequency characteristics is hard. These are other
problems in using the conventional extruded plastic films.

Prior art processes for fabricating printed circuit
boards propose stamping out a thick metallic foil into a
predetermined circuit pattern and adhering the resulting
circuit to a substrate. This process, however, is not
suitable for resonant tags and the like because a flexible
board cannot be obtained from a thick metallic foil. A
process for fabricating a flexible circuit proposes die
stamping, which comprises adhering a metallic foil to a
substrate and stamping out the metallic foil into a
predetermined circuit pattern, and peeling off the metallic
foil from the unnecessary portions. However, this process is
disadvantageous in that it excludes the use of a metallic
foil not strong enough for the peeling off, and that the
peeling efficiency is greatly impaired if unnecessary portion
is discontinuous.

SUMMARY OF THE INVENTION

~~Accordingly, an object of the present invention is to~~

~~overcome the aforementioned problems in prior art, and to~~
provide, by a simple fabrication process, a resonant tag
having a stable resonant frequency characteristics.

Another object of the present invention is to provide,
with high efficiency and without utilizing an etching
process, a resonant tag having a stable resonant
frequency characteristics and a circuit-like metallic foil
for use in circuit boards of various types of electric
appliances, heaters, etc., in which a wiring circuit similar
to that used in resonant tag is used.

BRIEF DESCRIPTION OF THE DRAWINGS

Fig. 1 is an exploded perspective view of a resonant
tag according to an embodiment of the present invention;

Fig. 2 is an exploded perspective view of a resonant
tag according to another embodiment of the present invention;

Fig. 3 is an exploded perspective view of a resonant
tag according to a still other embodiment of the present
invention;

Fig. 4 is a perspective view of a resonant tag
according to a yet other embodiment of the present invention,
in which an electrically conductive resin film is partially
provided to the resin film;

Fig. 5 is an exploded perspective view of a resonant
~~tag according to an embodiment of the present invention, in~~

~~4. A process for fabricating a circuit-like metallic foil sheet, said processing comprising:~~

~~providing a predetermined circuit-like pattern on a metallic foil of a first laminate comprising a carrier sheet adhered thereto the metallic foil, by means of patterning using a stamping die;~~

~~superposing on said patterned first laminate, a second laminate comprising a carrier sheet adhered thereto a metallic sheet being patterned by means of patterning using a stamping die; and~~

~~heating said circuit-like patterned portions form the carrier sheet side of either or both of the first and the second laminates, thereby forming circuit-like metallic foils on both sides of said support with hot-melt adhesive films being interposed therebetween.~~

5. A process for fabricating a circuit-like metallic foil sheet as claimed in claim 1, wherein the metallic foils are adhered to the carrier sheets using an easily removable adhesive.

6. A process for fabricating a circuit-like metallic foil sheet as claimed in claim 5, wherein the adhesive used for adhering the metallic foils to the carrier sheets is characterized in that it comprises a blend of an adhesion

~~14. A process for fabricating a resonant tag as claimed in claim 13, wherein a second laminate comprising a thermal adhesive dielectric resin film formed on the surface of the metal foil is used.~~

15. A resonant tag fabricated according to a process as claimed in claim 11.

16. A resonant tag comprising a circuit-like metallic foil being adhered to either or both sides of a dielectric film prepared from a liquid resin by a coating process.

17. A resonant tag as claimed in claim 16, wherein the dielectric resin film is provided on one side of the metallic foil and in the same shape as that of the circuit-like metallic foil.

18. A resonant tag as claimed in claim 17, wherein the dielectric resin film is laminated on one side of the metallic foil and has an area corresponding to that of a shape defined by the outer periphery of the circuit-like metallic foil.

19. A resonant tag as claimed in claim 16, wherein the ~~dielectric resin film is made of an adhesive resin.~~

~~20. A resonant tag comprising two or more laminates of circuit-like metallic foils having on at least one side thereof a dielectric resin film prepared from a liquid resin by a coating process, said metallic foils being laminated using the dielectric resin coating as an adhesive.~~

21. A resonant tag in which an adhesion adhesive is coated on at least one face of a resonant tag base and a release paper is applied on the upper face of the adhesive-coated base, the resonant tag characterized in that the adhesion adhesive is coated in such a manner that noncoated portion of the adhesion adhesive is provided at appropriate width.

22. A resonant tag claimed in claim 21, wherein the noncoated ~~portion is in a linear shape or a lattice shape.~~

23. ~~A method for deactivating resonant frequency~~
characteristics of the resonant tag as claimed in claim 16,
wherein a short-circuit is caused to generate at a portion
such as a bent portion of a coil circuit which is electrically
weak so as to destroy a resonant circuit, by sending strong
resonant frequencies to the resonant circuit.

24. A method for deactivating resonant frequency
characteristics as claimed in claim 23, wherein the resonant
tag is a tag in which the coil circuits or the resonant
circuit are in correspondence with each other and laminated
to a dielectric film so that the coil circuits sandwich the
~~dielectric film.~~